

NXP announces the first leadless package with tin-plated, solderable side pads

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NXP Semiconductors today announced the availability of SOD882D, the industry's first leadless package with solderable, tin-plated side pads.

The SOD882D is a 2-pin plastic [package](#) measuring only 1mm x 0.6mm and is ideal for small and thin devices. With a height of only 0.37 mm (typical), it is also one of the flattest packages in the 1006-size (0402 inch) and is available in various ESD protection and switching diodes.

The NXP SOD882D package has two tin-plated, solderable bottom pads that are exposed and are also Sn-plated on the sides. This innovative pad design provides soldering of the bottom and side pads and allows for easy visual inspection. The new package enables mechanically robust

designs as it is optimized for maximum shear forces, board bending and reduces the package tilting angle. The thermal, electrical, mounting and footprint characteristics of SOD882D are fully compatible with other available 2-pin, leadless 1006-packages.

“Leveraging our expertise in discrete leadless package technologies, NXP has developed the SOD882D package’s new pad design as an upgraded version of the successful SOD882. As one of the industry leaders in small-signal discretes, we believe that the SOD882D is a solution to a gap in the packaging market for highly space-constrained devices such as mobile phones, tablet PCs and small handheld devices requiring special mounting and robustness,” said Ralf Euler, Director of product management for small-signal discretes at NXP Semiconductors. “The SOD882D is a great new addition to NXP’s leadless packaging portfolio, which is already very broad and offers almost every discrete functionality.”

The first products to be available in the SOD882D package are a 100V single high-speed switching diode (BAS16LD) and three 5V and 24V ESD protection diodes (PESD*LD) that are designed to protect one signal line up to 30 kV (IEC 61000-4-2; level 4). All products are AEC-Q101 qualified and values for line capacitance range between 23 and 152 pF (typical). Two 5V ESD protection diodes with only 1.05 pF and 11 pF (typical) will be launched later this year. The portfolio will also include Schottky and low capacitance ESD protection diodes which will be introduced later this year and in early 2011. The SOD882D is free of halogens and antimony oxides and complies with non-flammability classification UL 94V-O and RoHS standards.

Source: NXP

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